CD4009UB, CD4010B Types

CMOS Hex Buffers/Converters

High-Voltage Types (20-Volt Rating)

Inverting Type: CD4009UB
Non-Inverting Type: CD4010B

■ CD4009UB and CD4010B Hex Buffer/Converters may be used as CMOS to TTL or DTL logic-level converters or CMOS high-sink-current drivers.

The CD4049UB and CD4050B are preferred hex buffer replacements for the CD4009UB and CD4010B, respectively, in all applications except multiplexers. For applications not requiring high sink current or voltage conversion, the CD4069UB Hex Inverter is recommended.
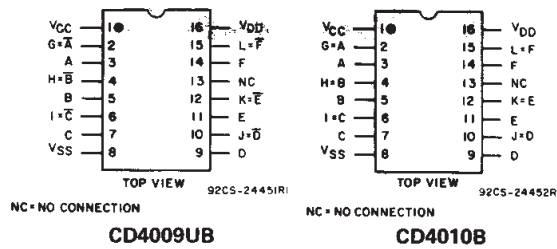
The CD4009UB and CD4010B types are supplied in 16-lead hermetic dual-in-line ceramic packages (F3A suffix), 16-lead dual-in-line plastic packages (E suffix), 16-lead small-outline packages (M, M96, MT, and NSR suffixes), and 16-lead thin shink small-outline packages (PW and PWR suffixes).

Features:

■ 100% tested for quiescent current at 20 V
■ Maximum input current of 1 μA at 18 V over full package-temperature range; 100 nA at 18 V and 25°C
■ 5-V, 10-V, and 15-V parametric ratings

Applications:

■ CMOS to DTL/TTL hex converter
■ CMOS current "sink" or "source" driver
■ CMOS high-to-low logic-level converter
■ Multiplexer — 1 to 6 or 6 to 1

CD4009UB FUNCTIONAL DIAGRAM

CD4010B FUNCTIONAL DIAGRAM

CD4009UB
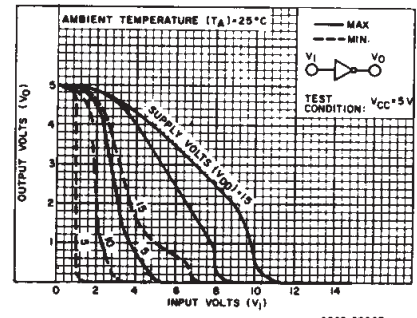

CD4010B

NC = NO CONNECTION

TERMINAL ASSIGNMENTS

Fig. 3 — Minimum and maximum voltage transfer characteristics—CD4009UB.

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V_{DD})
  Voltages referenced to V_{SS} Terminal) .... –0.5V to +20V
INPUT VOLTAGE RANGE, ALL INPUTS .... –0.5V to V_{DD} +0.5V
DC INPUT CURRENT, ANY ONE INPUT .... ±10mA
POWER DISSIPATION PER PACKAGE (P_D):
  For T_A = –55°C to +100°C 500mW
  For T_A = +100°C to +125°C................................. Derate Linearity at 12mW/°C to 200mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR
  FOR T_A = FULL PACKAGE-TEMPERATURE RANGE (All Package Types) 100mW
OPERATING-TEMPERATURE RANGE (T_A)..–55°C to +125°C
STORAGE TEMPERATURE RANGE (T_{stg})...–65°C to +150°C
LEAD TEMPERATURE (DURING SOLDERING):
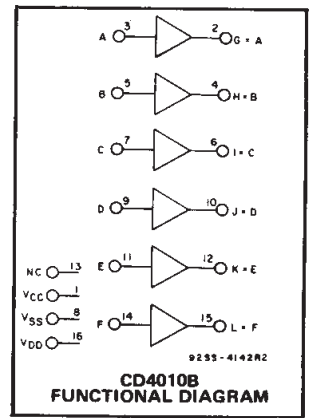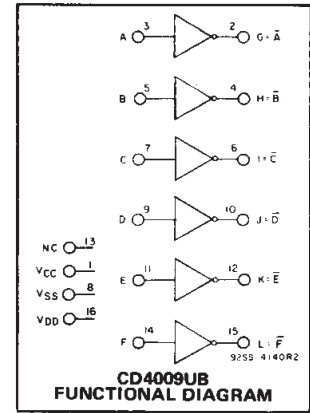 At distance 1/16 ± 1/32 inch (1.59 ± 0.79mm) from case for 10s max .... +265°C
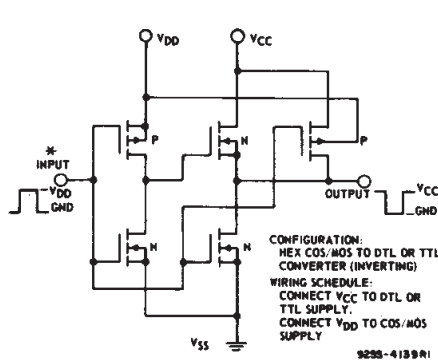

Fig. 1 — Schematic diagram of CD4009UB—
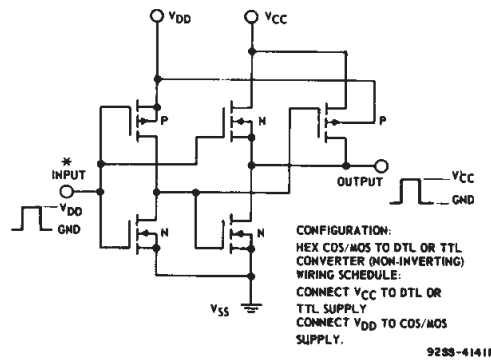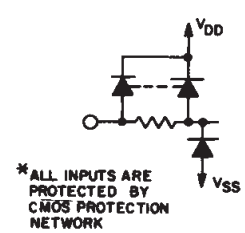1 of 6 identical stages.

Fig. 2 — Schematic diagram of CD4010B—
1 of 6 identical stages.

*ALL INPUTS ARE PROTECTED BY CMOS PROTECTION NETWORK

CD4009UB, CD4010B Types

RECOMMENDED OPERATING CONDITIONS

For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	MIN.	MAX.	
Supply-Voltage Range (For T_A = Full Package Temperature Range), V_{DD}	3	18	V
V_{CC}*	3	V_{DD}	
Input Voltage Range (V_I)	V_{CC}*	V_{DD}	V

*The CD4009UB and CD4010B have high-to-low level voltage conversion capability but not low-to-high level, therefore it is recommended that $V_{DD} \geqslant V_I \geqslant V_{CC}$.

STATIC ELECTRICAL CHARACTERISTICS

| CHARAC-TERISTIC	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)							UNITS
	V_O (V)	V_{IN} (V)	V_{DD} (V)	−55	−40	+85	+125	+25			
								Min.	Typ.	Max.	
Quiescent Device Current, I_{DD} Max.	−	0,5	5	1	1	30	30	−	0.02	1	μA
	−	0,10	10	2	2	60	60	−	0.02	2	
	−	0,15	15	4	4	120	120	−	0.02	4	
	−	0,20	20	20	20	600	600	−	0.04	20	
Output Low (Sink) Current I_{OL} Min.	0.4	0,5	4.5	3.2	3.1	2.1	1.8	2.6	3.4	−	mA
	0.4	0,5	5	3.75	3.6	2.4	2.1	3	4	−	
	0.5	0,10	10	10	9.6	6.4	5.6	8	10	−	
	1.5	0,15	15	30	40	19	16	24	36	−	
Output High (Source) Current I_{OH} Min.	4.6	0,5	5	−0.25	−0.23	−0.18	−0.15	−0.2	−0.4	−	
	2.5	0,5	5	−1	−0.9	−0.65	−0.58	−0.8	−1.6	−	
	9.5	0,10	10	−0.55	−0.5	−0.38	−0.33	−0.45	−0.9	−	
	13.5	0,15	15	−1.65	−1.6	−1.25	−1.1	−1.5	−3	−	
Output Voltage: Low-Level, V_{OL} Max.	−	0,5	5	0.05				−	0	0.05	V
	−	0,10	10	0.05					0	0.05	
	−	0,15	15	0.05				−	0	0.05	
Output Voltage: High-Level, V_{OH} Min.	−	0,5	5	4.95				4.95	5	−	
	−	0,10	10	9.95				9.95	10	−	
	−	0,15	15	14.95				14.95	15	−	
Input Low Voltage: V_{IL} Max. CD4009UB	4.5	−	5	1				−	−	1	V
	9	−	10	2				−	−	2	
	13.5	−	15	2.5				−	−	2.5	
Input Low Voltage: V_{IL} Max. CD4010B	0.5	−	5	1.5				−	−	1.5	
	1	−	10	3				−	−	3	
	1.5	−	15	4				−	−	4	
Input High Voltage: V_{IH} Min. CD4009UB	0.5	−	5	4			4		−	−	V
	1	−	10	8			8		−	−	
	1.5	−	15	12.5			12.5		−	−	
Input High Voltage: V_{IH} Min. CD4010B	4.5	−	5	3.5			3.5		−	−	
	9	−	10	7			7		−	−	
	13.5	−	15	11			11		−	−	
Input Current, I_{IN} Max.	−	0,18	18	±0.1	±0.1	±1	±1	−	$\pm 10^{-5}$	±0.1	μA
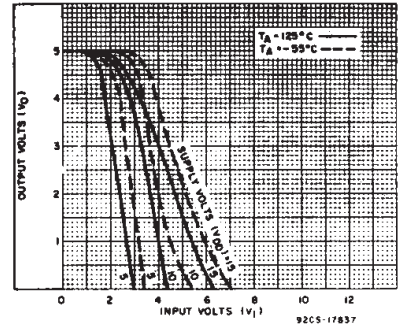
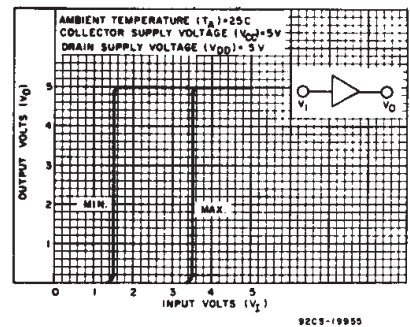Fig. 4 — Typical voltage transfer characteristics as function of temp.—CD4009UB.

Fig. 5 — Minimum and maximum voltage transfer characteristics (V_{DD}=5)—CD4010B.
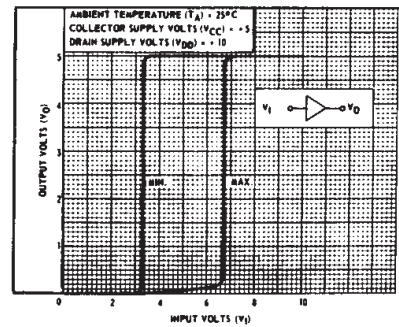

Fig. 6 — Minimum and maximum voltage transfer characteristics (V_{DD}=10)—CD4010B.
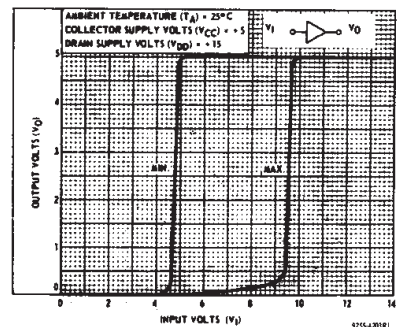

Fig. 7 — Minimum and maximum voltage transfer characteristics (V_{DD}=15)—CD4010B.

CD4009UB, CD4010B Types

DYNAMIC ELECTRICAL CHARACTERISTICS *at $T_A=25°C$; Input t_r, $t_f=20$ ns, $C_L=50$ pF, $R_L=200$ KΩ*

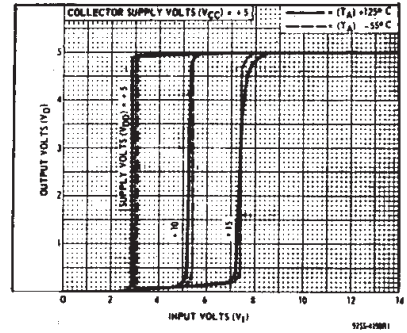| CHARACTERISTIC	CONDITIONS			LIMITS ALL PKGS		UNIT
	V_{DD} (V)	V_I (V)	V_{CC} (V)	TYP.	MAX.	
Propagation Delay Time: Low-to-High, t_{PLH}	5	5	5	70	140	
	10	10	10	40	80	
CD4009UB	10	10	5	35	70	ns
	15	15	15	30	60	
	15	15	5	30	60	
	5	5	5	100	200	
	10	10	10	50	100	
CD4010B	10	10	5	50	100	ns
	15	15	15	35	70	
	15	15	5	35	70	
High-to-Low, t_{PHL}	5	5	5	30	60	
	10	10	10	20	40	
CD4009UB	10	10	5	15	30	ns
	15	15	15	15	30	
	15	15	5	10	20	
	5	5	5	65	130	
	10	10	10	35	70	
CD4010B	10	10	5	30	70	ns
	15	15	15	25	50	
	15	15	5	20	40	
Transition Time: Low-to-High, t_{TLH}	5	5	5	150	350	
	10	10	10	75	150	ns
	15	15	15	55	110	
High-to-Low, t_{THL}	5	5	5	35	70	
	10	10	10	20	40	ns
	15	15	15	15	30	
Input Capacitance, C_{IN} CD4009UB	—	—	—	15	22.5	
CD4010B	—	—	—	5	7.5	pF

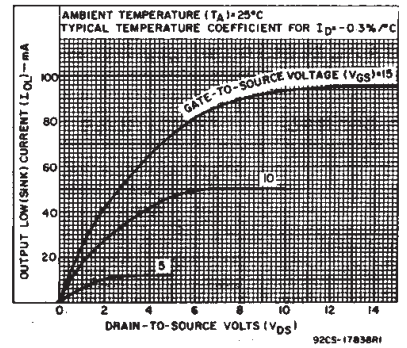Fig. 8 — Typical voltage transfer characteristics as a function of temperature—CD4010B.

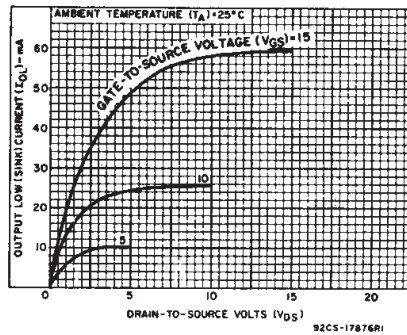Fig. 9 — Typical output low (sink) current characteristics.

Fig. 10 — Minimum output low (sink) current characteristics.
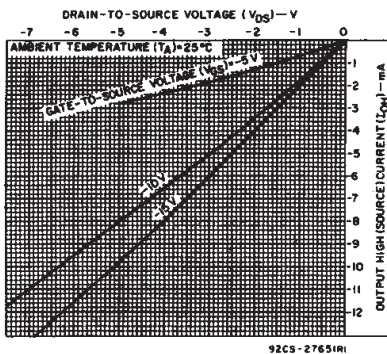

Fig. 11 — Typical output high (source) current characteristics.
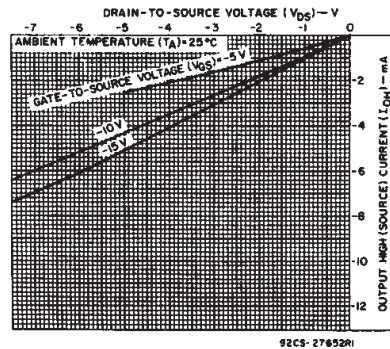

Fig. 12 — Minimum output high (source) current characteristics.
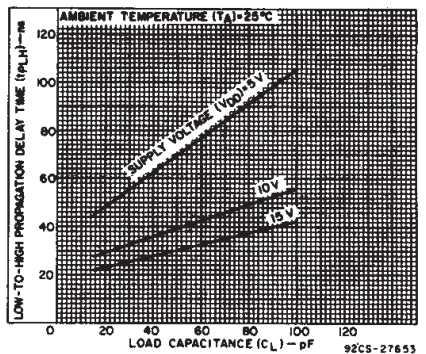
Fig. 13 — Typical low-to-high propagation delay time vs. load capacitance (CD4009UB).
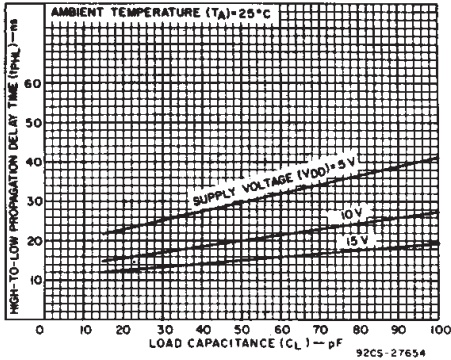
Fig. 14 — Typical high-to-low propagation delay
time vs. load capacitance (CD4009UB).
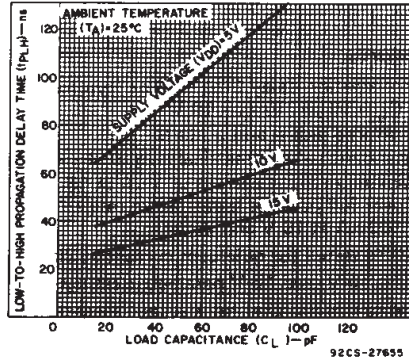
Fig. 15 — Typical low-to-high propagation delay
time vs. load capacitance (CD4010B).
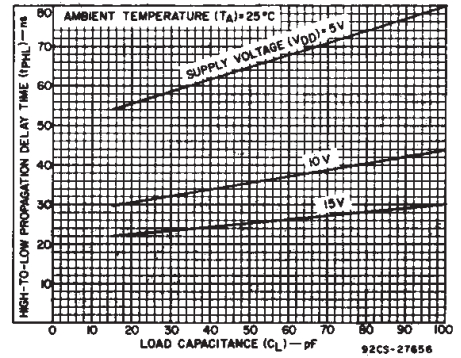
Fig. 16 — Typical high-to-low propagation
delay time vs. load capacitance (CD4010B).
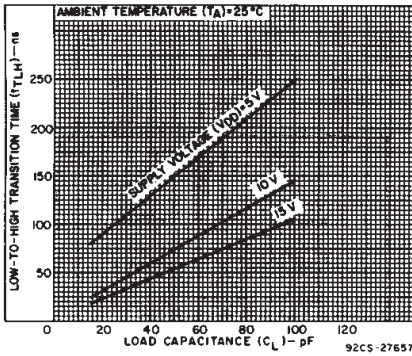
Fig. 17 — Typical low-to-high transition time
vs. load capacitance.
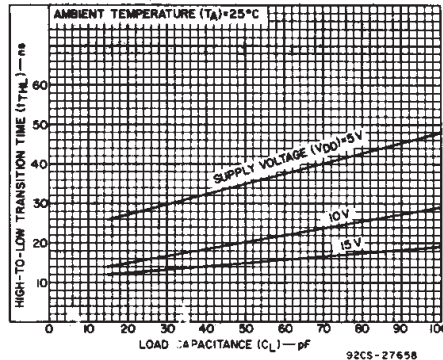
Fig. 18 — Typical high-to-low transition time
vs. load capacitance.
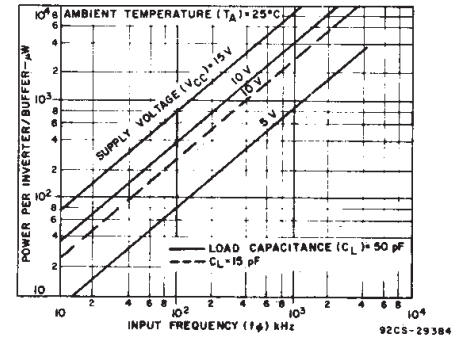
Fig. 19 — Typical dissipation characteristics.
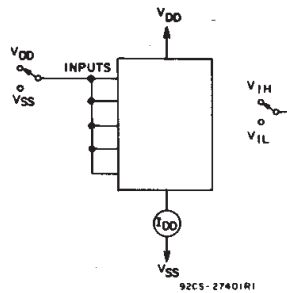
Fig. 20 — Quiescent device current
test circuit.

Fig. 21 — Noise immunity test
circuit.

NOTE:
TEST ANY ONE INPUT,
WITH OTHER INPUTS AT
V_{DD} OR V_{SS}.

NOTE:
MEASURE INPUTS
SEQUENTIALLY,
TO BOTH V_{DD} AND V_{SS}.
CONNECT ALL UNUSED
INPUTS TO EITHER
V_{DD} OR V_{SS}.

Fig. 22 — Input current test
circuit.
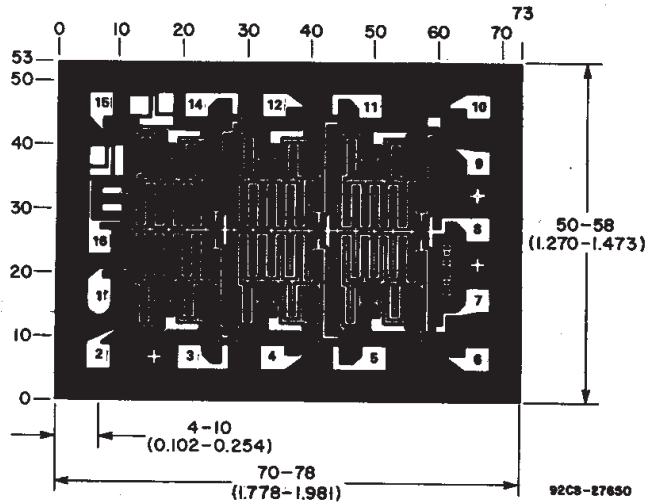
Dimensions in parentheses are in millimeters and are
derived from the basic inch dimensions as indicated.
Grid Graduations Are In Mils (10^{-3} Inch)

Photograph of chip for CD4009UB.
Dimensions and pad layout for
CD4010B are identical.

PACKAGING INFORMATION

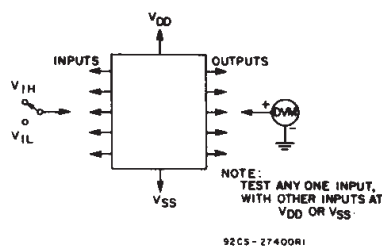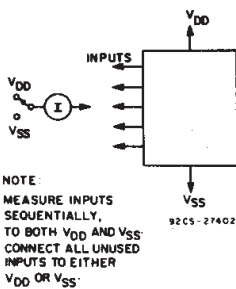| Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/ Ball Finish	MSL Peak Temp [3]	Samples (Requires Login)
89264UKB3T	OBSOLETE	CFP	WR	16		TBD	Call TI	Call TI	Samples Not Available
CD4009UBE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
CD4009UBEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
CD4009UBF	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	Purchase Samples
CD4009UBF3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	Purchase Samples
CD4009UBM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4009UBME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4009UBMG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4009UBMT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4009UBMTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4009UBMTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4009UBPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
CD4009UBPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
CD4009UBPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
CD4010BE	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
CD4010BEE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	Contact TI Distributor or Sales Office
CD4010BF	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	Purchase Samples
CD4010BF3A	ACTIVE	CDIP	J	16	1	TBD	A42	N / A for Pkg Type	Purchase Samples
CD4010BM	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples

Orderable Device	Status [1]	Package Type	Package Drawing	Pins	Package Qty	Eco Plan [2]	Lead/ Ball Finish	MSL Peak Temp [3]	Samples (Requires Login)
CD4010BM96	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4010BM96E4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4010BM96G4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4010BME4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4010BMG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4010BMT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4010BMTE4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4010BMTG4	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4010BNSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4010BNSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4010BNSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4010BPW	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4010BPWE4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4010BPWG4	ACTIVE	TSSOP	PW	16	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Purchase Samples
CD4010BPWR	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
CD4010BPWRE4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office
CD4010BPWRG4	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	Contact TI Distributor or Sales Office

[1] The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF CD4009UB, CD4009UB-MIL, CD4010B, CD4010B-MIL :

● Catalog: CD4009UB, CD4010B

● Automotive: CD4010B-Q1, CD4010B-Q1

● Military: CD4009UB-MIL, CD4010B-MIL

NOTE: Qualified Version Definitions:

 ● Catalog - TI's standard catalog product

 ● Automotive - Q100 devices qualified for high-reliability automotive applications targeting zero defects

 ● Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSIONS

Reel Diameter

Reel Width (W1)

A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

Sprocket Holes

| Q1 | Q2 |
| Q3 | Q4 |

User Direction of Feed

Pocket Quadrants

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CD4009UBPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
CD4010BM96	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
CD4010BNSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
CD4010BPWR	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CD4009UBPWR	TSSOP	PW	16	2000	346.0	346.0	29.0
CD4010BM96	SOIC	D	16	2500	333.2	345.9	28.6
CD4010BNSR	SO	NS	16	2000	346.0	346.0	33.0
CD4010BPWR	TSSOP	PW	16	2000	346.0	346.0	29.0

J (R-GDIP-T**)   CERAMIC DUAL IN-LINE PACKAGE
14 LEADS SHOWN

DIM PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	——	——	——	——
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)

0.065 (1,65)
0.045 (1,14)

0.005 (0,13) MIN

0.060 (1,52)
0.015 (0,38)

0.200 (5,08) MAX

Seating Plane

0.130 (3,30) MIN

0.026 (0,66)
0.014 (0,36)

0.100 (2,54)

0.014 (0,36)
0.008 (0,20)

0°–15°

4040083/F 03/03

NOTES: A.   All linear dimensions are in inches (millimeters).
         B.   This drawing is subject to change without notice.
         C.   This package is hermetically sealed with a ceramic lid using glass frit.
         D.   Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
         E.   Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

N (R−PDIP−T**)

PLASTIC DUAL−IN−LINE PACKAGE

16 PINS SHOWN

DIM / PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS−001 VARIATION (C)	AA	BB	AC	AD

0.260 (6,60) / 0.240 (6,10)

0.070 (1,78) / 0.045 (1,14) (D)

0.045 (1,14) / 0.030 (0,76) (D)

0.020 (0,51) MIN

0.200 (5,08) MAX

Seating Plane

0.125 (3,18) MIN

0.100 (2,54)

0.021 (0,53) / 0.015 (0,38)

⊕ 0.010 (0,25) (M)

14/18 Pin Only
20 Pin vendor option (D)

0.325 (8,26) / 0.300 (7,62)

0.015 (0,38)

Gauge Plane

0.010 (0,25) NOM

0.430 (10,92) MAX

4040049/E 12/2002

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
         C. Falls within JEDEC MS−001, except 18 and 20 pin minimum body length (Dim A).
         D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

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D (R−PDSO−G16)   PLASTIC SMALL OUTLINE

$\frac{0.394\ (10,00)}{0.386\ (9,80)}$ ⬠C

16   9

$\frac{0.244\ (6,20)}{0.228\ (5,80)}$

$\frac{0.157\ (4,00)}{0.150\ (3,80)}$ ⬠D

1   8

Pin 1
Index Area

0.050 (1,27)

$\frac{0.020\ (0,51)}{0.012\ (0,31)}$

⊕ 0.010 (0,25) Ⓜ

0.069 (1,75) Max

$\frac{0.010\ (0,25)}{0.004\ (0,10)}$

$\frac{0.010\ (0,25)}{0.005\ (0,13)}$

0.004 (0,10)

Gauge Plane

Seating Plane

0.010 (0,25)   0°−8°
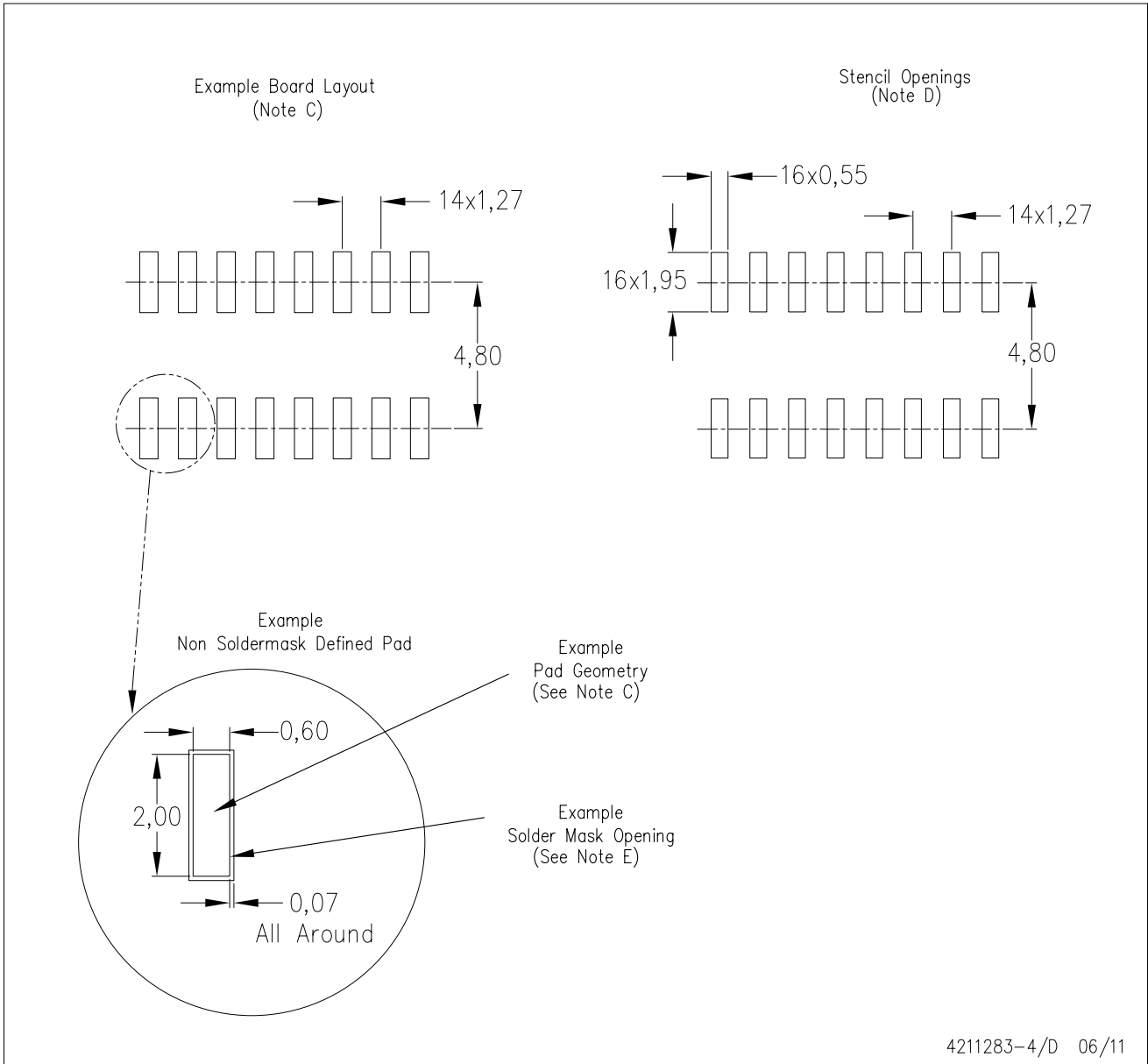
$\frac{0.050\ (1,27)}{0.016\ (0,40)}$

4040047−6/M   06/11

NOTES: A. All linear dimensions are in inches (millimeters).
         B. This drawing is subject to change without notice.
      ⬠C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
             not exceed 0.006 (0,15) each side.
      ⬠D Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
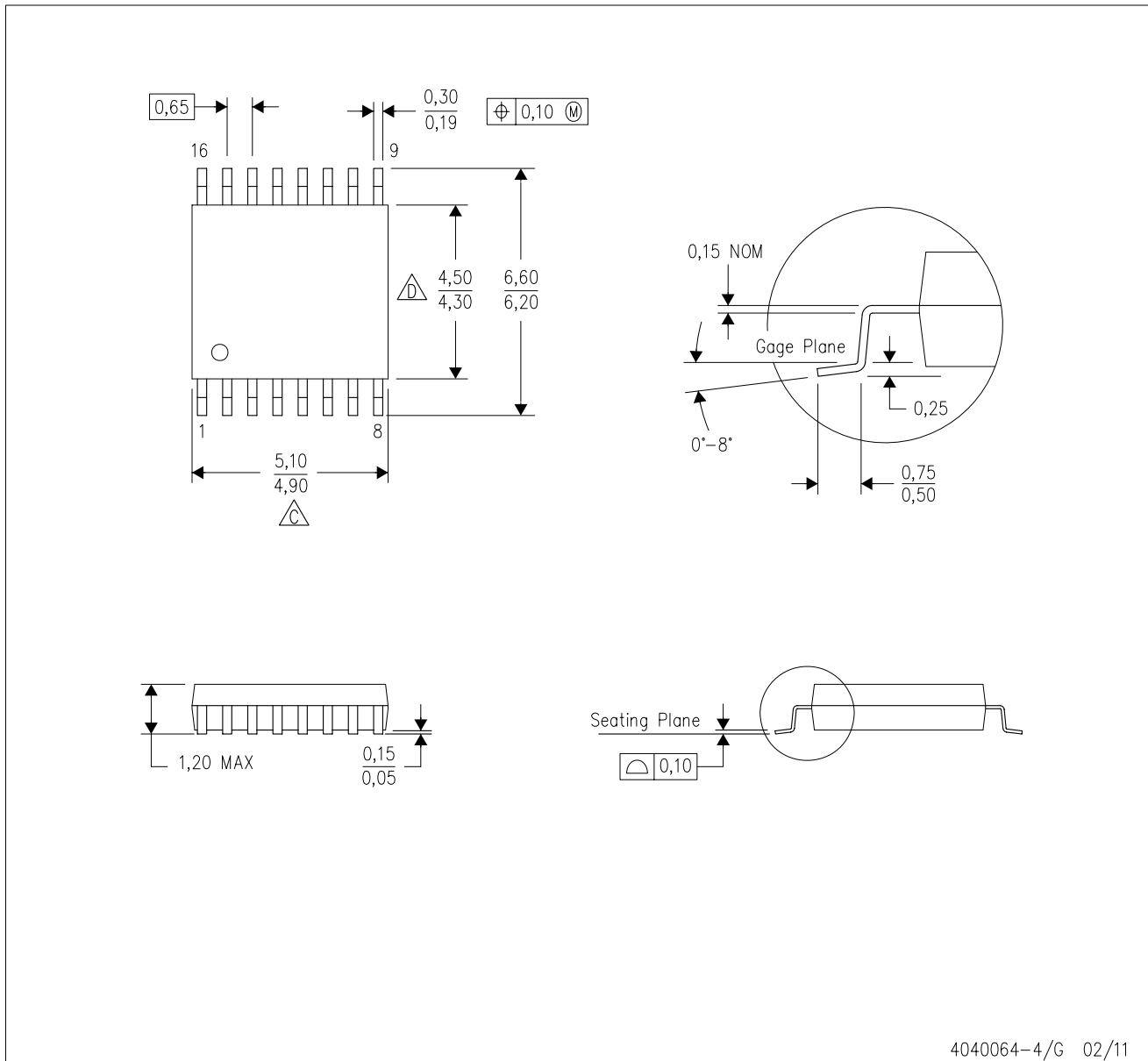   E. Reference JEDEC MS−012 variation AC.

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D (R–PDSO–G16)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

14x1,27

16x0,55

14x1,27

16x1,95

4,80

4,80

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

0,60

2,00

Example
Solder Mask Opening
(See Note E)

0,07
All Around

4211283–4/D   06/11

NOTES: A.   All linear dimensions are in millimeters.
          B.   This drawing is subject to change without notice.
          C.   Publication IPC–7351 is recommended for alternate designs.
          D.   Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
               contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
          E.   Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

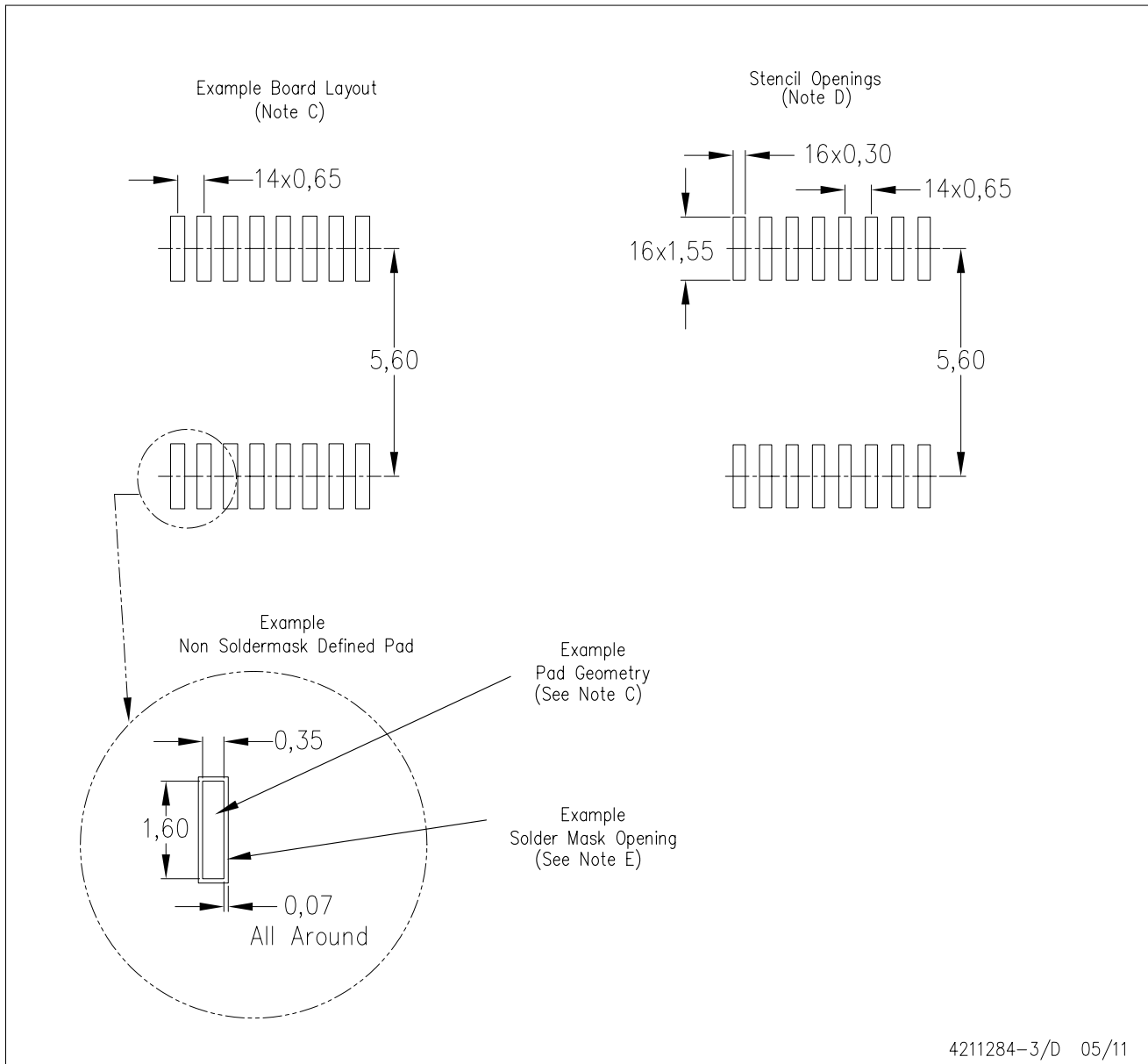PW (R−PDSO−G16)   PLASTIC SMALL OUTLINE

0,65

0,30
0,19

⊕ 0,10 Ⓜ

16   9

△D 4,50
    4,30   6,60
               6,20

1   8

5,10
4,90

△C

0,15 NOM

Gage Plane

0°−8°

0,25

0,75
0,50

1,20 MAX   0,15
                0,05

Seating Plane
⌒ 0,10

4040064−4/G 02/11

NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M−1994.
        B. This drawing is subject to change without notice.
       △C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall
            not exceed 0,15 each side.
       △D Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
        E. Falls within JEDEC MO−153

PW (R−PDSO−G16)   PLASTIC SMALL OUTLINE

Example Board Layout
(Note C)

Stencil Openings
(Note D)

14x0,65

16x0,30

14x0,65

16x1,55

5,60

5,60

Example
Non Soldermask Defined Pad

Example
Pad Geometry
(See Note C)

0,35

1,60

Example
Solder Mask Opening
(See Note E)

0,07
All Around

4211284−3/D   05/11

NOTES: A.   All linear dimensions are in millimeters.
         B.   This drawing is subject to change without notice.
         C.   Publication IPC−7351 is recommended for alternate designs.
         D.   Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should
              contact their board assembly site for stencil design recommendations. Refer to IPC−7525 for other stencil recommendations.
         E.   Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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MECHANICAL DATA

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN

PINS ** DIM	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES: A.   All linear dimensions are in millimeters.
          B.   This drawing is subject to change without notice.
          C.   Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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